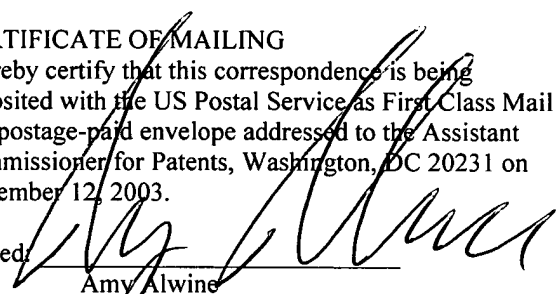


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>Re application of: Basol et al.</p> <p>Serial No.: 10/663,318</p> <p>Filed: September 16, 2003</p> <p>Title: Conductive Structure Fabrication Process Using Novel Layered Structure And Conductive Structure Fabricated Thereby For Use In Multi-Level Metallization</p>	<p>Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-108C1-US</p> <p>CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the US Postal Service as First Class Mail in a postage-paid envelope addressed to the Assistant Commissioner for Patents, Washington, DC 20231 on November 12, 2003.</p> <p>Signed:  Amy Alwine</p>
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**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Trademarks  
Washington, D.C. 20231

Dear Sir:

Applicants submit information herewith to comply with the obligations set forth in 37 CFR §1.56. A copy of an International Search Report dated June 27, 2001 is also submitted. These submissions are not an admission that any of the documents are prior art or otherwise relevant to the subject application.

This IDS is submitted:

- ☐ with a filed patent application or within 3 months of the US application filing date;  
☒ before the mailing of a first office action on the merits;  
☐ after the first office action, but prior to a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) or a certification set forth below; or  
☐ after a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) and a certification set forth below, where this submission is a petition requesting consideration of this IDS.

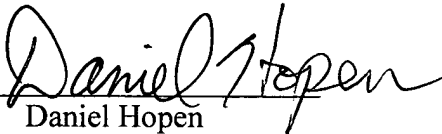
If identified above, Applicant certifies that:

- ☐ the information was first cited in a communication from a foreign patent office in a counterpart foreign application less than 3 months prior to this IDS; or

☐ to the knowledge of the person signing this certification after making reasonable inquiry, the information was not known to any individuals designated in 37 CFR §1.56 more than 3 months prior to this IDS.

If any matters can be resolved by telephone, Applicant requests that the Patent and Trademark Office call the Applicant at the telephone number listed below.

Respectfully submitted,

By:   
Daniel Hopen  
Reg. No. 35,547

NuTool, Inc.  
Legal Department  
1655 McCandless Drive  
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(408) 586-9500x268



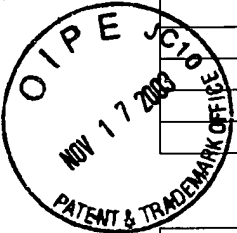
# UNITED STATES PATENT AND TRADEMARK OFFICE

<p>In re application of:</p> <p>Basol et al.</p> <p>Serial No.: 10/663,318</p> <p>Filed: September 16, 2003</p> <p>Title: Conductive Structure Fabrication Process Using Novel Layered Structure And Conductive Structure Fabricated Thereby For Use In Multi-Level Metallization</p>	<p>Group Art Unit: Not yet assigned</p> <p>Examiner: Not yet assigned</p> <p>Docket: NT-108C1-US</p>
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## INFORMATION DISCLOSURE STATEMENT

### US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
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	AB	6,176,992	January, 2001	Talieh	In Serial No. 09/642,827
	AC	6,136,163	October, 2000	Cheung et al.	In Serial No. 09/642,827
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	BK	PCT 98/27585	June, 1998	Deligianni et al.	In Serial No. 09/642,827	
	BL	WO 00/26443	May, 2000	Talieh	In Serial No. 09/642,827	

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	BM	James J. Kelly et al., "Leveling and Microstructural Effects of Additives for Copper Electrodeposition", Journal of the Electrochemical Society, 146 (7), 1999, Pages 2540-2545	In Serial No. 09/642,827	
	BN	Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials", A Wiley-Interscience Publication, 1997 by John Wiley & Sons, Inc. pages 212-222.	In Serial No. 09/642,827	
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Examiner Signature		Date Considered	
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